

Amendments to the Claims

Claims 1-93 (**Canceled**)

Claim 94 (**Previously Presented**) An apparatus for processing a substrate, said apparatus comprising:

a plating unit having a plating chamber for electroplating a substrate having fine grooves in a surface of the substrate and a seed layer on a surface of the fine grooves; and

an annealing unit having a chamber for annealing the substrate,

wherein said plating unit is structured to form a plated film on the seed layer by electroplating with supplying a first current by a voltage to the seed layer and then supplying a second current to the seed layer.

Claim 95 (**Previously Presented**) An apparatus according to claim 94, wherein the second current is larger than the first current.

Claim 96 (**Previously Presented**) An apparatus according to claim 94, wherein said plating unit is structured to apply a reverse voltage to the seed layer for thereby etching the plated film formed on the substrate.

Claims 97 and 98 (**Canceled**)